LM2575

52 kHz Simple 1A Buck Regulator

Features

- 3.3V, 5V, 12V, and Adjustable Output Versions
- Voltage over Specified Line and Load Conditions:
  - Fixed Version: ±3% Max. Output Voltage
  - Adjustable Version: ±2% Max. Feedback Voltage
- Ensured 1A Output Current
- Wide Input Voltage Range: 4V to 40V
- Wide Output Voltage Range: 1.23V to 37V
- Requires only Four External Components
- 52 kHz Fixed Frequency Internal Oscillator
- Low Power Standby Mode: I_Q Typically <200 µA
- 80% Efficiency (Adjustable Version Typically >80%)
- Uses Readily Available Standard Inductors
- Thermal Shutdown and Current Limit Protection
- 100% Electrical Thermal Limit Burn-In

Applications

- Simple High-Efficiency Step-Down (Buck) Regulator
- Efficient Pre-Regulator for Linear Regulators
- On-Card Switching Regulators
- Positive-to-Negative Converter (Inverting Buck-Boost)
- Isolated Flyback Converter Using Minimum Number of External Components
- Negative Boost Converter

General Description

The LM2575 series of monolithic integrated circuits provide all the active functions for a step-down (buck) switching regulator. Fixed versions are available with a 3.3V, 5V, 12V, fixed output. Adjustable versions have an output voltage range from 1.23V to 37V. Both versions are capable of driving a 1A load with excellent line and load regulation.

These regulators are simple to use because they require a minimum number of external components and include internal frequency compensation as well as a fixed-frequency oscillator.

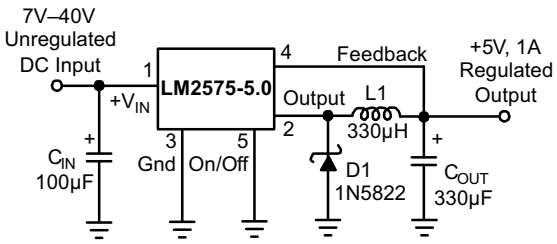
The LM2575 series offers a high efficiency replacement for popular three-terminal adjustable linear regulators. It substantially reduces the size of the heat sink and, in many cases, no heat sink is required.

A standard series of inductors available from several different manufacturers are ideal for use with the LM2575 series. This feature greatly simplifies the design of switch-mode power supplies.

The feedback voltage is ensured to ±2% tolerance for adjustable versions and the output voltage is ensured to ±3% for fixed versions within specified input voltages and output load conditions. The oscillator frequency is ensured to ±10%. External shutdown is included, featuring less than 200 µA of standby current. The output switch includes cycle-by-cycle current limiting and thermal shutdown for full protection under fault conditions.

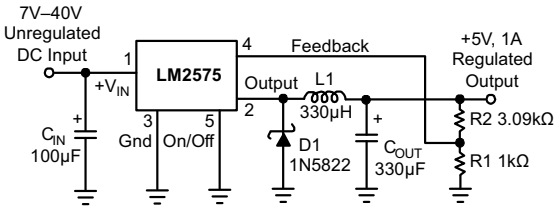
Typical Application Circuits

Fixed Output Voltage Option



Note: Pin numbers are for TO-220 Package

Adjustable Output Voltage Option

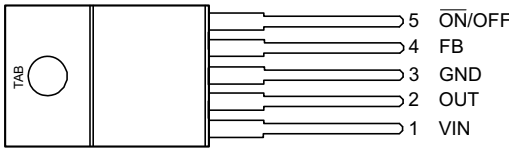


Note: Pin numbers are for TO-220 Package

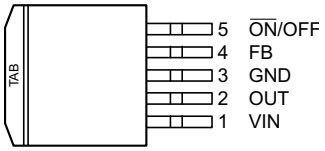
$$V_{OUT} = 1.23 \left(1 + \frac{R2}{R1}\right)$$

Package Types

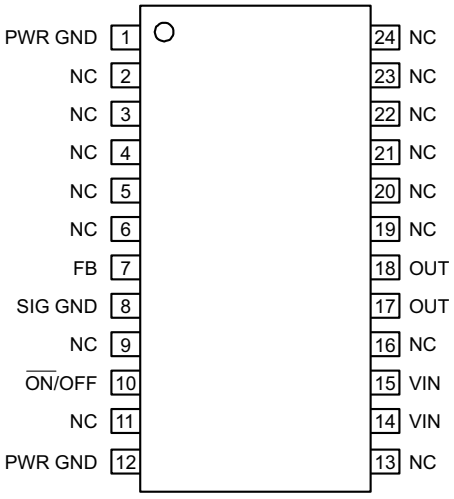
LM2575
5-Lead TO-220 (T)
(Top View)



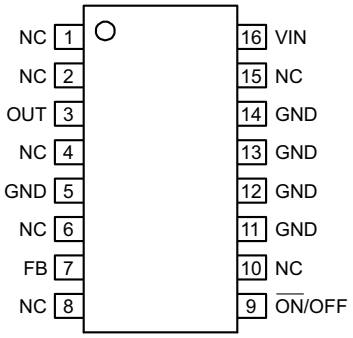
LM2575
5-Lead TO-263 (U)
(Top View)



LM2575
24-Lead Wide SOIC (WM)
(Top View)

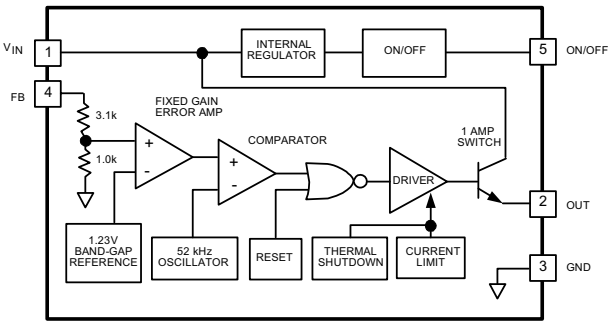


LM2575
16-Lead PDIP (N)
(Top View)



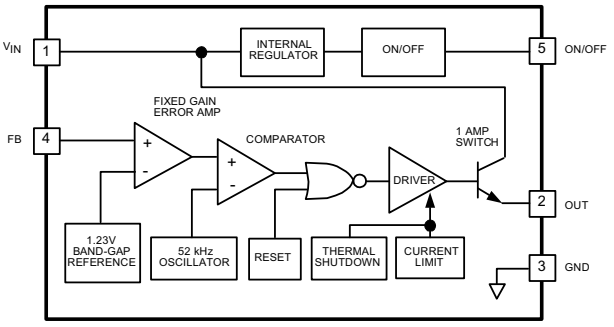
Functional Block Diagrams

Fixed Output Voltage Option



Note: Pin numbers are for the TO-220 package

Adjustable Output Voltage Option



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Maximum Supply Voltage (V_{IN}) ..... +45V
ON/OFF Pin Input Voltage ..... –0.3V ≤ V ≤ +40V
Output Voltage to Ground (Steady State) ..... –1V
Power Dissipation ..... Internally Limited
ESD Rating (Note 1) ..... 2 kV
ESD Rating (FB Pin) ..... 1 kV

Operating Ratings ‡

Supply Voltage (V_{IN}) ..... +40V

† Notice: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

‡ Notice: The device is not guaranteed to function outside its operating ratings.

Note 1: C = 100 pF, R = 1.5kΩ.

ELECTRICAL CHARACTERISTICS

Specifications with standard typeface are for T_J = +25°C, and those with **boldface type** apply over the T_J range of –40°C to +85°C. Unless otherwise specified, V_{IN} = 12V and I_{LOAD} = 200 mA (Note 1).

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
System Parameters, Adjustable Regulators (Note 2) See Figure 1-1						
Feedback Voltage	V_{FB}	1.217	1.230	1.243	V	V_{IN} = 12V, I_{LOAD} = 0.2A V_{OUT} = 5V
		1.193	1.230	1.267	V	0.2A ≤ I_{LOAD} ≤ 1A, 8V ≤ V_{IN} ≤ 40V, V_{OUT} = 5V
		1.180	1.230	**1.280**		
Efficiency	η	—	82	—	%	V_{IN} = 12V, I_{LOAD} = 1A, V_{OUT} = 5V
System Parameters, 3.3V Regulators (Note 2) See Figure 1-1						
Output Voltage	V_{OUT}	3.234	3.3	3.366	V	V_{IN} = 12V, I_{LOAD} = 0.2A V_{OUT} = 3.3V
		3.168	3.3	3.432	V	0.2A ≤ I_{LOAD} ≤ 1A, 8V ≤ V_{IN} ≤ 40V, V_{OUT} = 3.3V
		3.135	3.3	**3.465**		
Efficiency	η	—	75	—	%	V_{IN} = 12V, I_{LOAD} = 1A
System Parameters, 5V Regulators (Note 2) See Figure 1-1						
Output Voltage	V_{OUT}	4.900	5.0	5.100	V	V_{IN} = 12V, I_{LOAD} = 0.2A V_{OUT} = 5V
		4.800	5.0	5.200	V	0.2A ≤ I_{LOAD} ≤ 1A, 8V ≤ V_{IN} ≤ 40V, V_{OUT} = 5V
		4.750	5.0	**5.250**		
Efficiency	η	—	82	—	%	V_{IN} = 12V, I_{LOAD} = 1A
System Parameters, 12V Regulators (Note 2) See Figure 1-1						
Output Voltage	V_{OUT}	11.760	12.0	12.240	V	V_{IN} = 25V, I_{LOAD} = 0.2A V_{OUT} = 12V
		11.520	12.0	12.480	V	0.2A ≤ I_{LOAD} ≤ 1A, 15V ≤ V_{IN} ≤ 40V, V_{OUT} = 12V
		11.400	12.0	**12.600**		
Efficiency	η	—	88	—	%	V_{IN} = 25V, I_{LOAD} = 1A

ELECTRICAL CHARACTERISTICS (CONTINUED)

Specifications with standard typeface are for T_J = +25°C, and those with **boldface type** apply over the T_J range of –40°C to +85°C. Unless otherwise specified, V_{IN} = 12V and I_{LOAD} = 200 mA (Note 1).

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Device Parameters, Adjustable Regulator						
Feedback Bias Current	I_{BIAS}	—	50	100	nA	V_{OUT} = 5V
		—	50	**500**		
Device Parameters, Fixed and Adjustable Regulators						
Oscillator Frequency	f_O	47	52	58	kHz	—
		42	52	**63**		
Saturation Voltage	V_{SAT}	—	0.9	1.2	V	I_{OUT} = 1A, Note 3
		—	0.9	**1.4**		
Max Duty Cycle (ON)	DC	93	98	—	%	Note 4
Current Limit	I_{LIM}	1.7	2.2	3.0	A	Peak Current, t_{ON} ≤ 3 µs, Note 3
		1.3	2.2	**3.2**		
Output Leakage Current Output = 0V	I_L	—	—	2	mA	V_{IN} = 40V, Note 5
Output Leakage Current Output = –1V		—	75	—		—
Output Leakage Current Output = +1V		—	—	30		Note 5
Quiescent Current	I_Q	—	5	10	mA	Note 5
Standby Quiescent Current	I_{STBY}	—	50	200	µA	ON/OFF Pin = 5V (OFF)
ON/OFF Control, Fixed and Adjustable Regulators, See Figure 1-1						
ON/OFF Pin Logic Input Level	V_{IH}	2.2	1.4	—	V	V_{OUT} = 0V
		2.4	1.4	—		
	V_{IL}	—	1.2	1.0		V_{OUT} = 5V
		—	1.2	**0.8**		
ON/OFF Pin Logic Current	I_{IH}	—	4	30	µA	ON /OFF Pin = 5V (OFF)
	I_{IL}	—	0.01	10	µA	ON /OFF Pin = 0V (ON)

Note 1: All limits ensured at room temperature (standard type face) and at **temperature extremes (bold type face)**. All room temperature limits are 100% production tested. All limits at **temperature extreme** are ensured via testing.

2: External components such as the catch diode, inductor, input and output capacitors can affect switching regulator system performance. When the LM2575 is used as shown in Figure 1-1 test circuit, system performance will be shown in system parameters section of Electrical Characteristics.

3: Output (pin 2) sourcing current. No diode, inductor or capacitor connected to output.

4: Feedback (pin 4) removed from output and connected to 0V.

5: Feedback (pin 4) removed from output and connected to 12V to force the output transistor OFF.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Maximum Junction Temperature	$T_{J(MAX)}$	—	—	+150	°C	—
Storage Temperature Range	T_S	–65	—	+150	°C	—
Lead Temperature	T_{LEAD}	—	—	260	°C	Soldering, 10 sec.
Junction Temperature Range	T_J	–40	—	+125	°C	—
Package Thermal Resistances						
Thermal Resistance, TO-220 5-Ld	θ_{JA}	—	65	—	°C/W	Note 1
	θ_{JA}	—	45	—	°C/W	Note 2
	θ_{JC}	—	2	—	°C/W	—
Thermal Resistance, PDIP 16-Ld	θ_{JA}	—	85	—	°C/W	Note 3
Thermal Resistance, Wide SOIC 24-Ld	θ_{JA}	—	100	—	°C/W	Note 3

Note 1: Junction to ambient thermal resistance (no external heat sink) for the 5-lead TO-220 package mounted vertically, with 1/2" leads in a socket, or on PC board with minimum copper area.

2: Junction to ambient thermal resistance (no external heat sink) for the 5-lead TO-220 package mounted vertically, with 1/4" leads soldered to PC board containing approximately 4 square inches of copper area surrounding the leads.

3: Junction to ambient thermal resistance with approximately 1 square inch of PC board copper surrounding the leads. Additional copper will lower thermal resistance further.

Test Circuits and Layout Guidelines

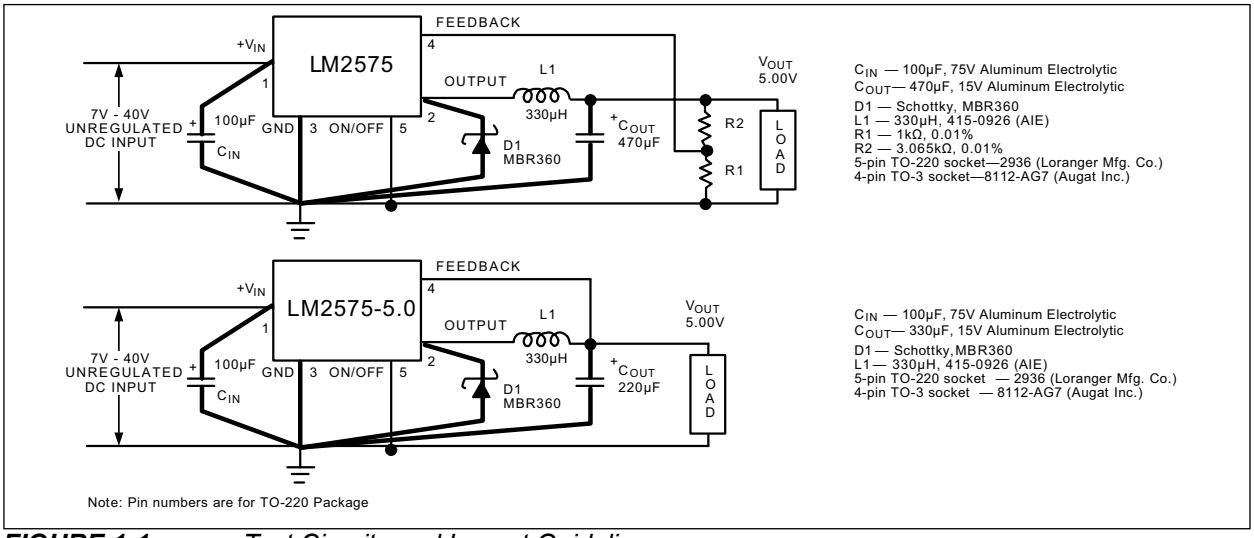


FIGURE 1-1: *Test Circuits and Layout Guidelines.*

As in any switching regulator, layout is very important. Rapidly switching currents associated with wiring inductance generate voltage transient switches that can cause problems. For minimal stray inductance and ground loops, the length of the leads indicated by heavy lines above should be kept as short as possible. Single-point grounding (as indicated) or ground plane construction should be used for best results.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

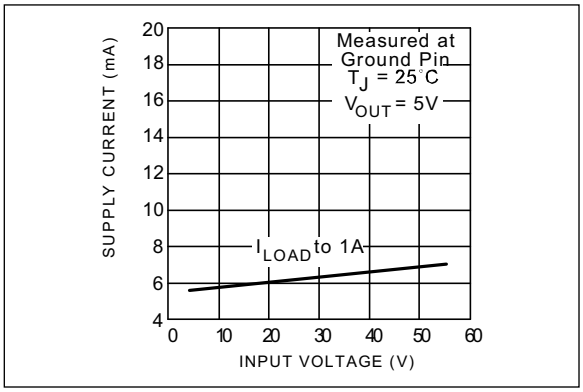


FIGURE 2-1: *Supply Current vs. Input Voltage.*

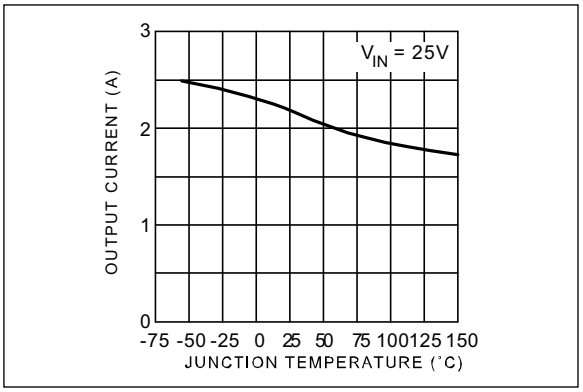


FIGURE 2-4: *Current Limit vs. Temperature.*

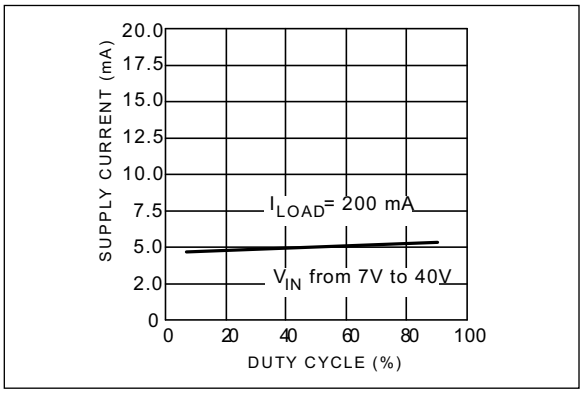


FIGURE 2-2: *Supply Current vs. Duty Cycle.*

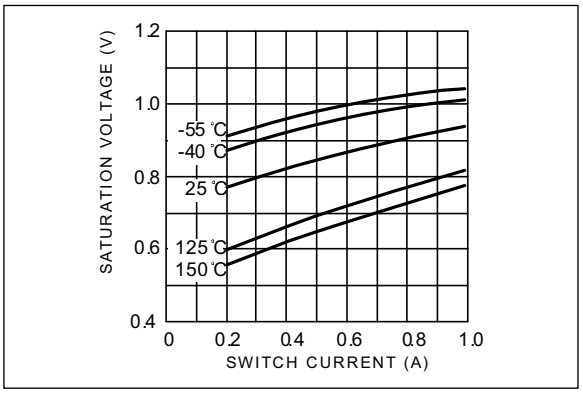


FIGURE 2-5: *Switch Saturation Voltage vs. Current.*

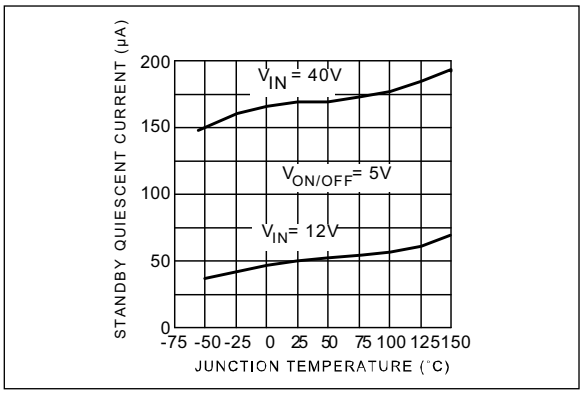


FIGURE 2-3: *Standby Quiescent Current vs. Temperature.*

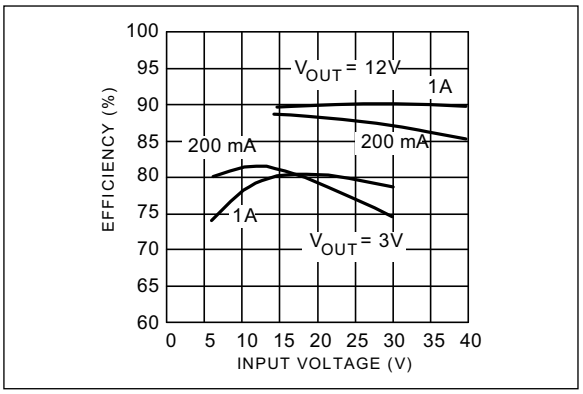


FIGURE 2-6: *Efficiency vs. Input Voltage.*

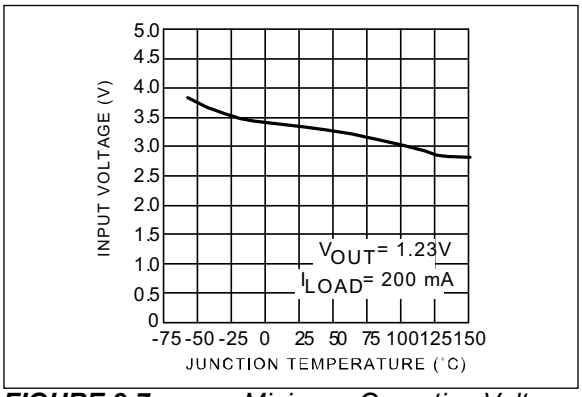


FIGURE 2-7: *Minimum Operating Voltage vs. Temperature.*

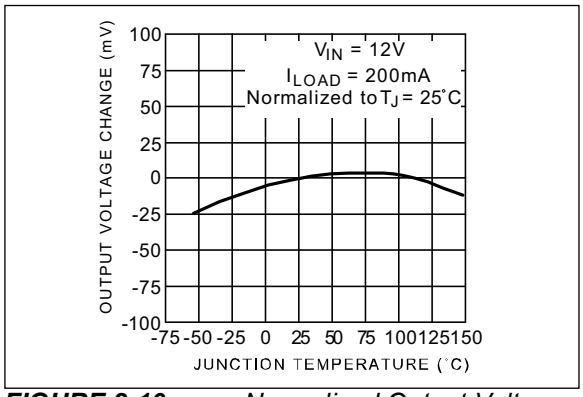


FIGURE 2-10: *Normalized Output Voltage vs. Temperature.*

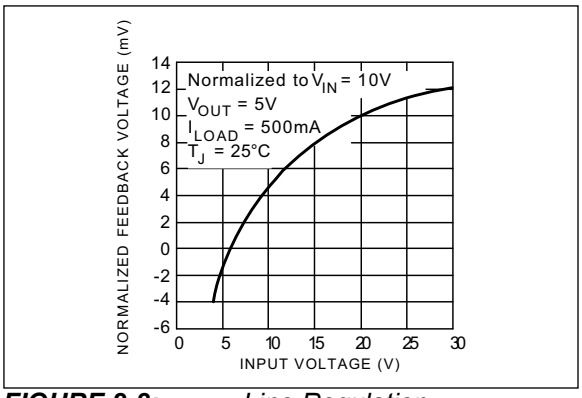


FIGURE 2-8: *Line Regulation.*

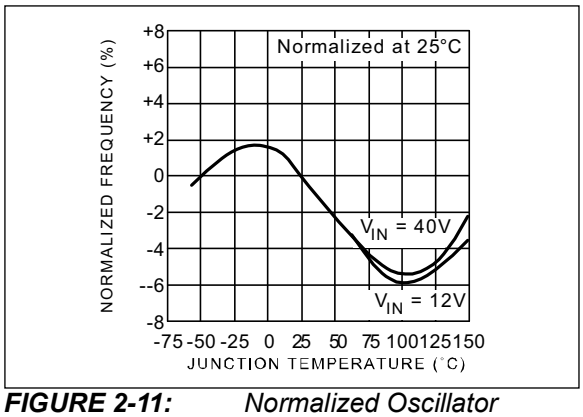


FIGURE 2-11: *Normalized Oscillator Frequency vs. Temperature.*

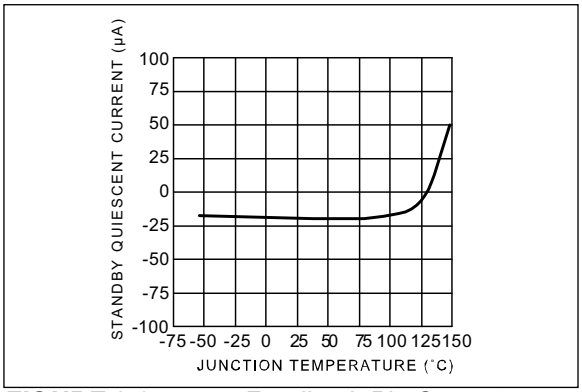


FIGURE 2-9: *Feedback Pin Current vs. Temperature.*

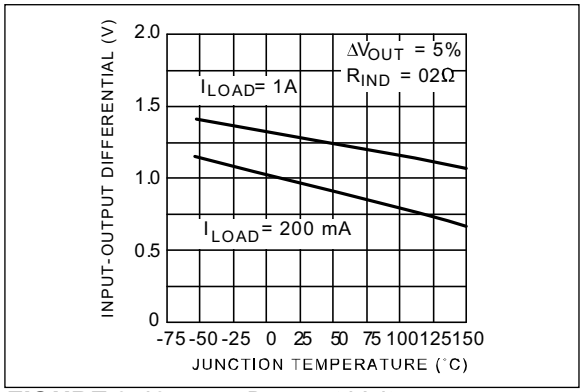


FIGURE 2-12: *Dropout Voltage vs. Temperature.*

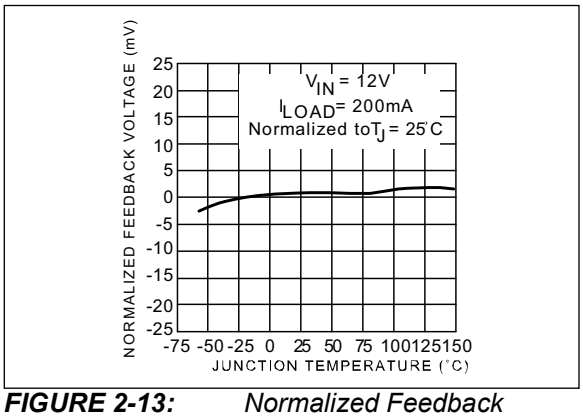


FIGURE 2-13: *Normalized Feedback Voltage vs. Temperature (Adjustable Version Only).*

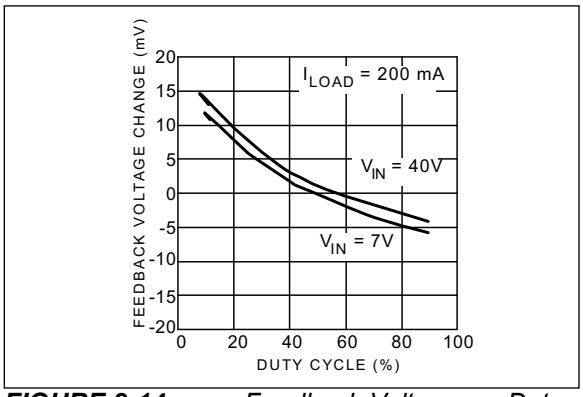


FIGURE 2-14: *Feedback Voltage vs. Duty Cycle (Adjustable Version Only).*

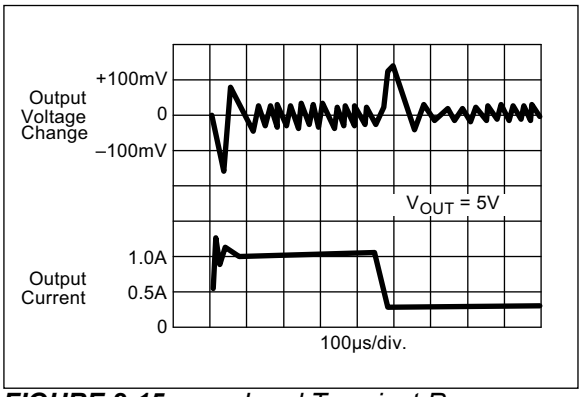


FIGURE 2-15: *Load Transient Response.*

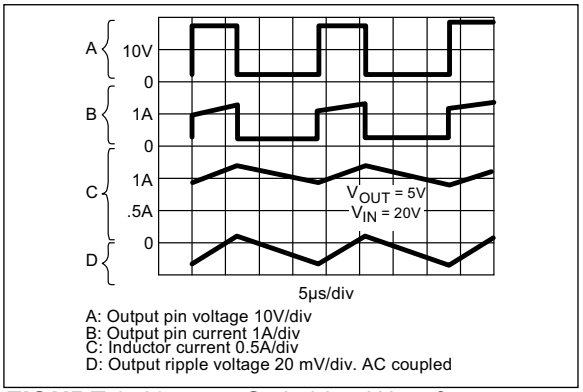
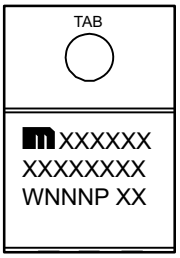


FIGURE 2-16: *Switching Waveforms.*

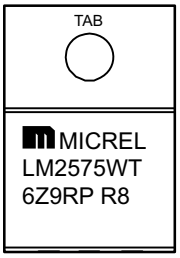
3.0 PACKAGING INFORMATION

3.1 Package Marking Information

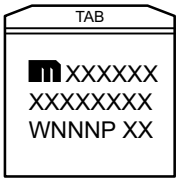
5-Lead TO-220*



Example



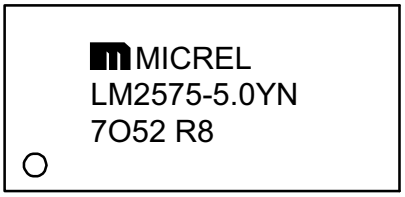
5-Lead TO-263*



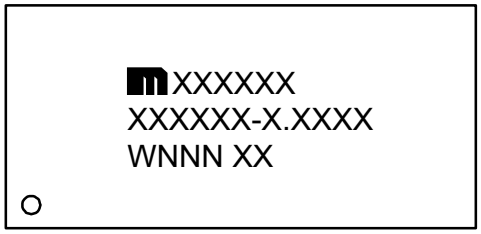
Example

16-Lead PDIP*

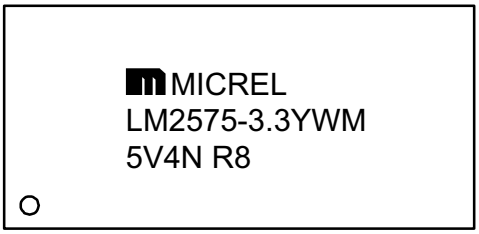
Example



24-Lead SOIC*



Example

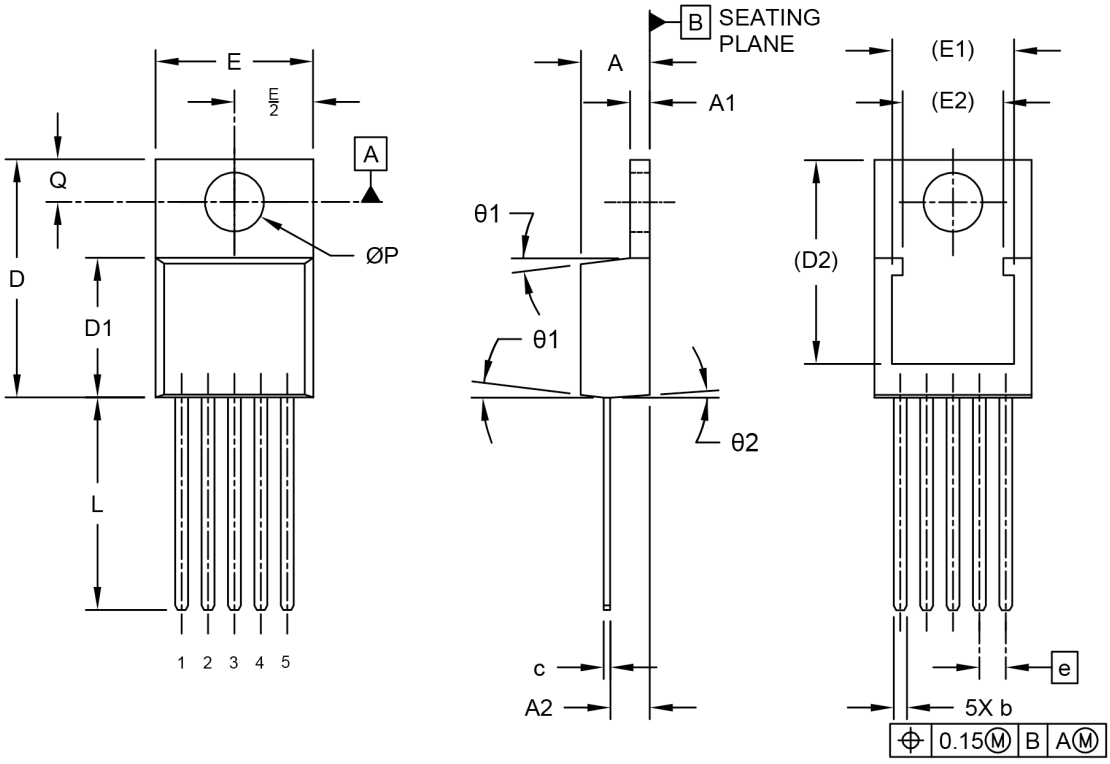


Legend:	XX...X	Product code or customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
	●, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).
Note:		In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.
		Underbar (_) and/or Overbar (¯) symbol may not be to scale.

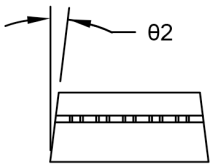
Note: If the full seven-character YYWWNNN code cannot fit on the package, the following truncated codes are used based on the available marking space:
6 Characters = YWWNNN; 5 Characters = WWNNN; 4 Characters = WNNN; 3 Characters = NNN;
2 Characters = NN; 1 Character = N

5-Lead Transistor Outline Type LB03 (B8X) - [TO-220]
Micrel Legacy Package TO220-LB03-5LD-PL-1

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW SIDE VIEW BOTTOM VIEW

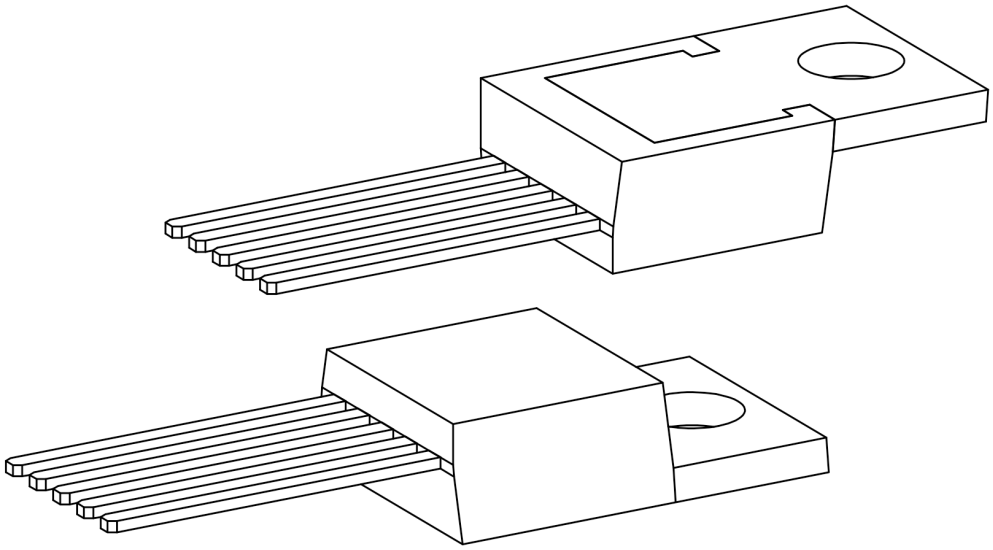


END VIEW

Microchip Technology Drawing C04-036-B8X Rev E Sheet 1 of 2

5-Lead Transistor Outline Type LB03 (B8X) - [TO-220]
Micrel Legacy Package TO220-LB03-5LD-PL-1

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES		
Dimension Limits		Min	Nom	Max
Number of Leads	N		5	
Pitch	e		.067 BSC	
Overall Height	A	.160	.175	.190
Tab Height	A1	.045	.050	.055
Seating Plane to Lead	A2	.080	.098	.115
Lead Width	b	.025	.033	.040
Lead Thickness	c	.012	.016	.020
Lead Length	L	.500	.540	.580
Total Body Length Including Tab	D	.542	.580	.619
Molded Body Length	D1	.348	.354	.360
Total Width	E	.380	.400	.420
Pad Width	E1		0.256 REF	
Pad Length	D2		0.486 REF	
Hole Diameter	ØP	.146	.151	.156
Hole Center to Tab Edge	Q	.103	.108	.113
Molded Body Draft Angle	θ1	3	7	10
Molded Body Draft Angle	θ2	1	4	7

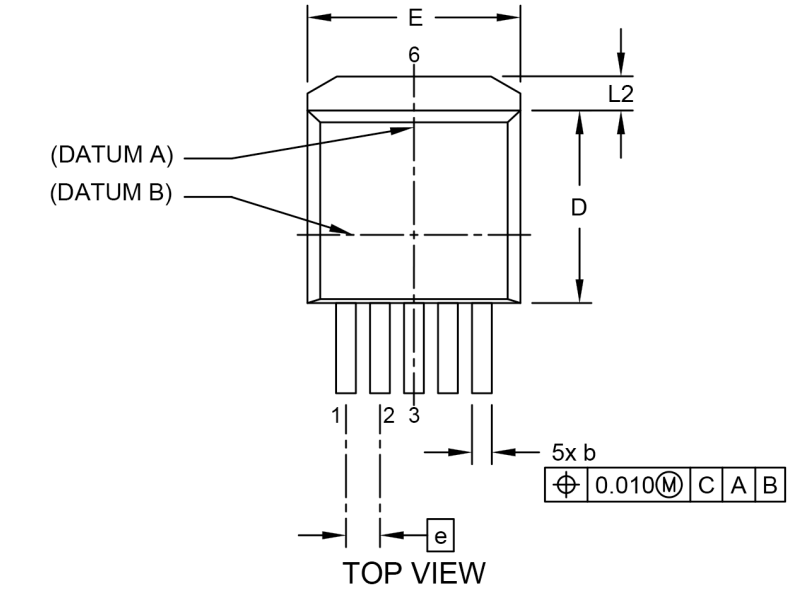
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

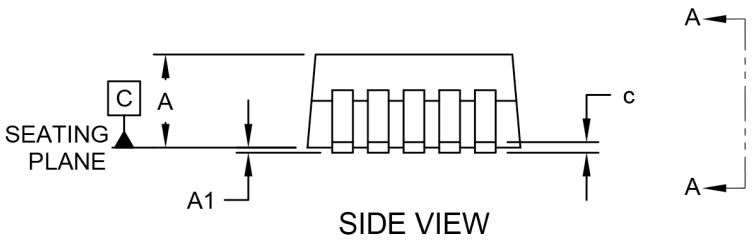
Microchip Technology Drawing C04-036-B8X Rev E Sheet 2 of 2

5-Lead Plastic Double Deca-Watt Package (J7X) [DDPAK]

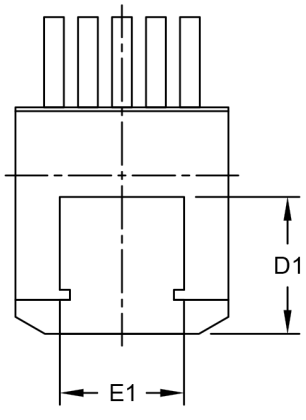
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

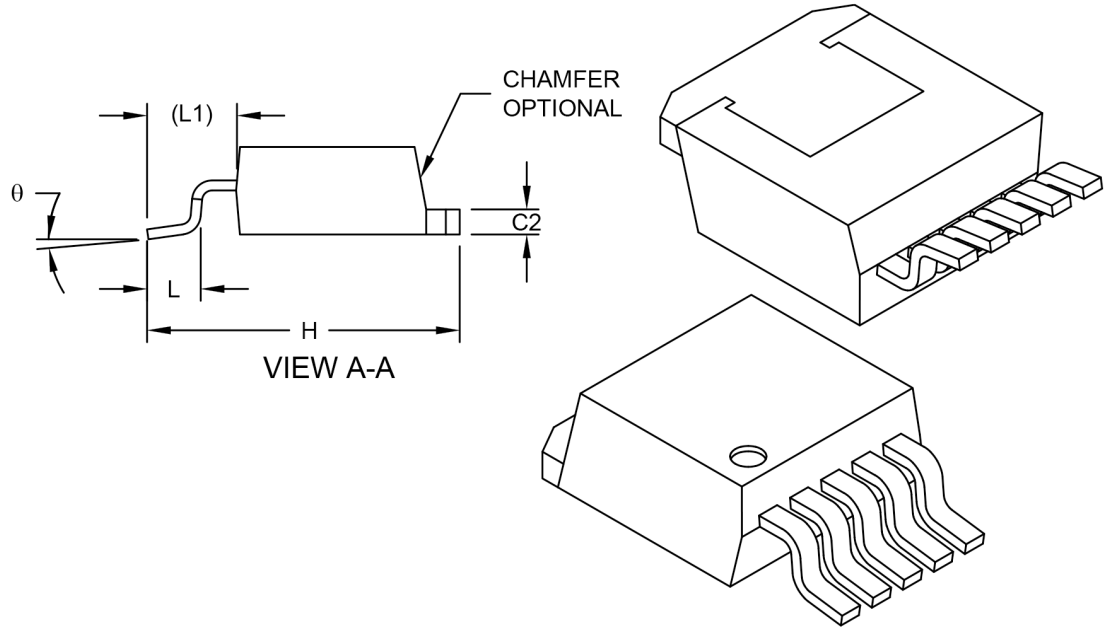


BOTTOM VIEW

Microchip Technology Drawing C04-00012 (J7X) Rev E Sheet 1 of 2

5-Lead Plastic Double Deca-Watt Package (J7X) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		5	
Pitch	e		.067 BSC	
Molded Package Thickness	A	.160	-	.190
Standoff	A1	.000	-	.010
Overall Length	H	.575	-	.625
Overall Width	E	.380	-	.420
Thermal Tab Width	E1	.245	-	-
Molded Package Length	D	.330	-	.380
Thermal Tab Length	D1	.270	-	-
Lead Thickness	c	.015	-	.029
Lead Width	b	.020	-	.039
Thermal Tab Thickness	C2	.045	-	.065
Lead Length	L	.070	-	.110
Foot Print Length	L1		0.13 REF	
Thermal Tab Length	L2	-	-	.066
Foot Angle	θ	0°	-	8°

Notes:

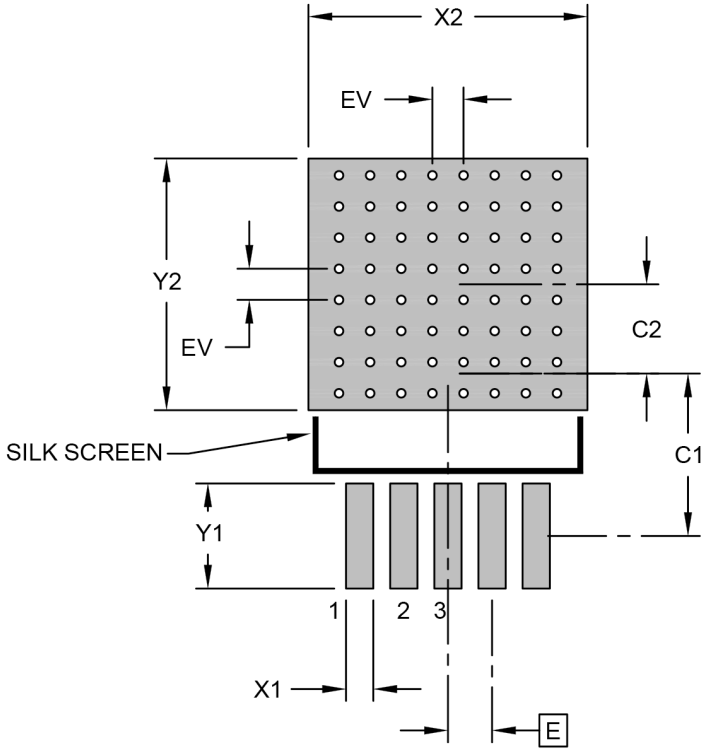
1. § Significant Characteristic
2. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. The theoretically exact value is shown without tolerances.

Microchip Technology Drawing C04-00012 (J7X) Rev E Sheet 2 of 2

5-Lead Plastic Double Deca-Watt Package (J7X) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	.067 BSC		
Optional Contact Pad Width	X2			.423
Optional Contact Pad Length	Y2			.382
Contact Pad Spacing	C1		.246	
Contact Pad Spacing	C2		.136	
Contact Pad Width (X3)	X1			.041
Contact Pad Length (X3)	Y1			.159
Thermal Via Diameter	V		.013	
Thermal Via Pitch	EV		.047	

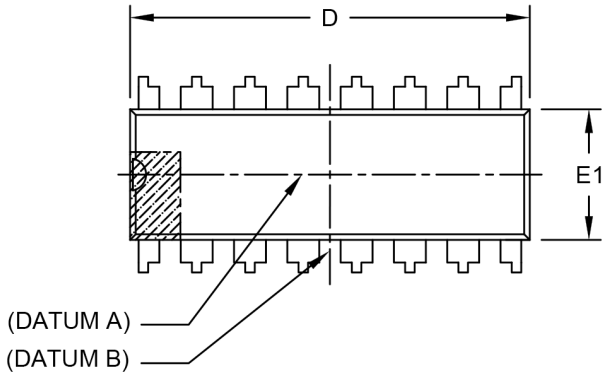
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during the reflow process.

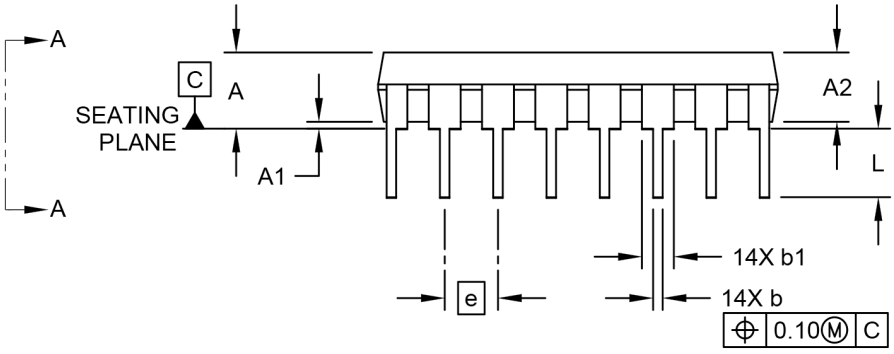
Microchip Technology Drawing C04-02012 (J7X) Rev E

16-Lead Plastic Dual In-Line (D6X) - 300 mil Body [PDIP]

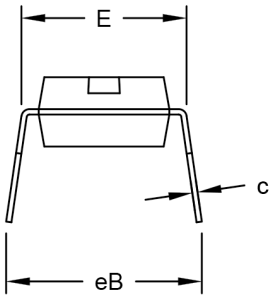
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

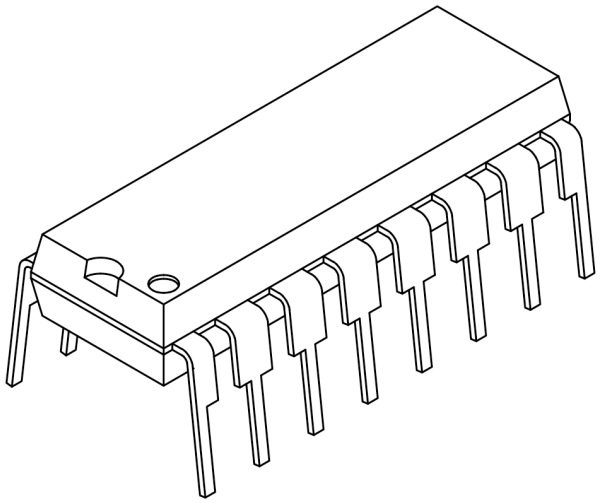


VIEW A-A

Microchip Technology Drawing C04-00017 Rev C (D6X) Sheet 1 of 2

16-Lead Plastic Dual In-Line (D6X) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		.100 BSC	
Top to Seating Plane	A	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.735	.750	.775
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	-	-	.430

Notes:

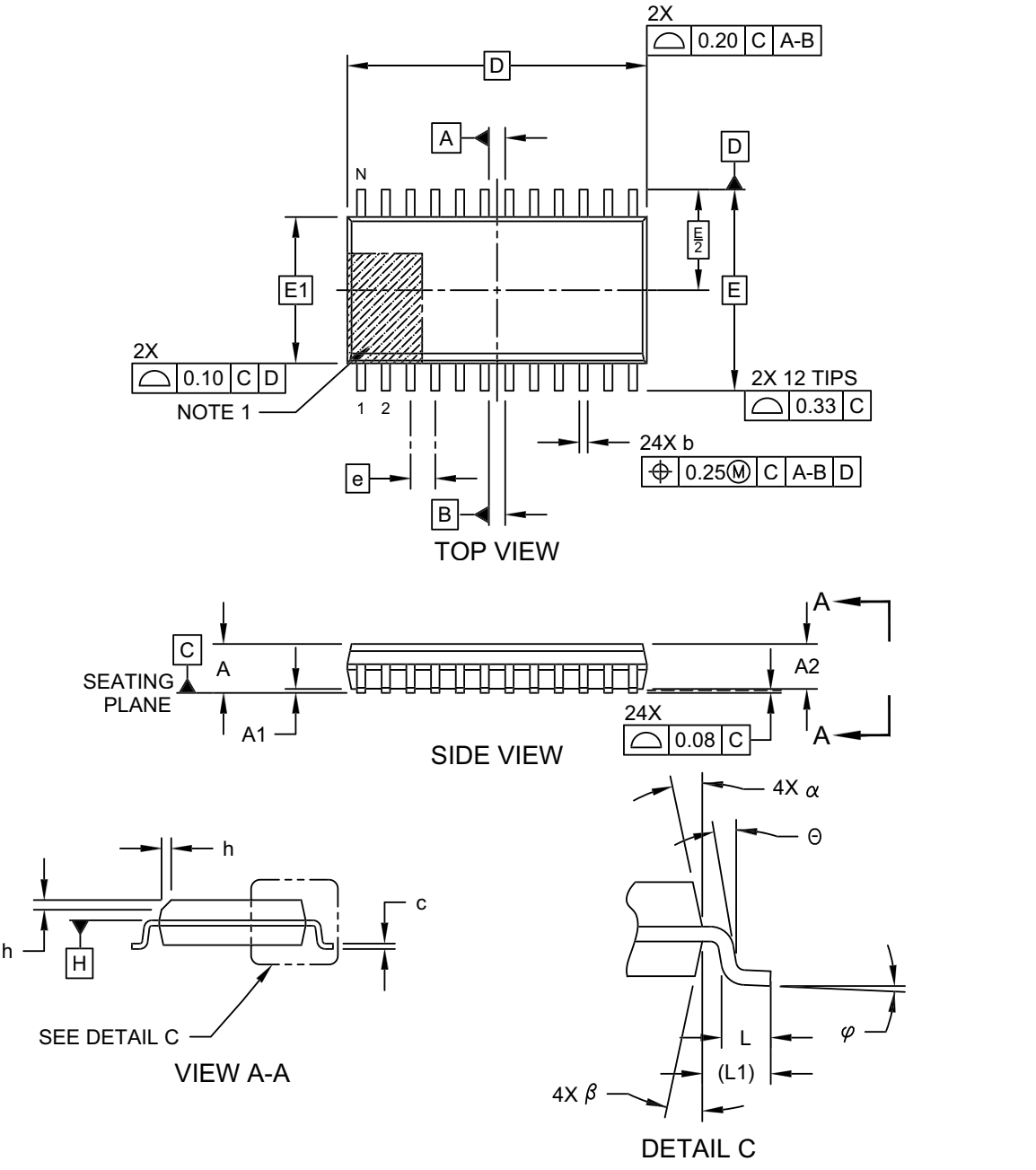
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-00017 Rev C (D6X) Sheet 2 of 2

24-Lead Plastic Small Outline (K3X) - Wide, 7.50 mm Body [SOIC]

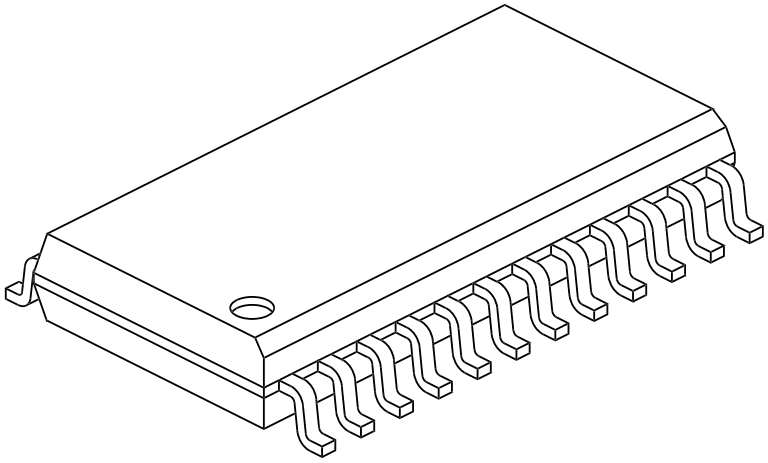
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-00025 [K3X] Rev F Sheet 1 of 2

24-Lead Plastic Small Outline (K3X) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		24	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		15.40 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. The Pin 1 visual index feature may vary, but it must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

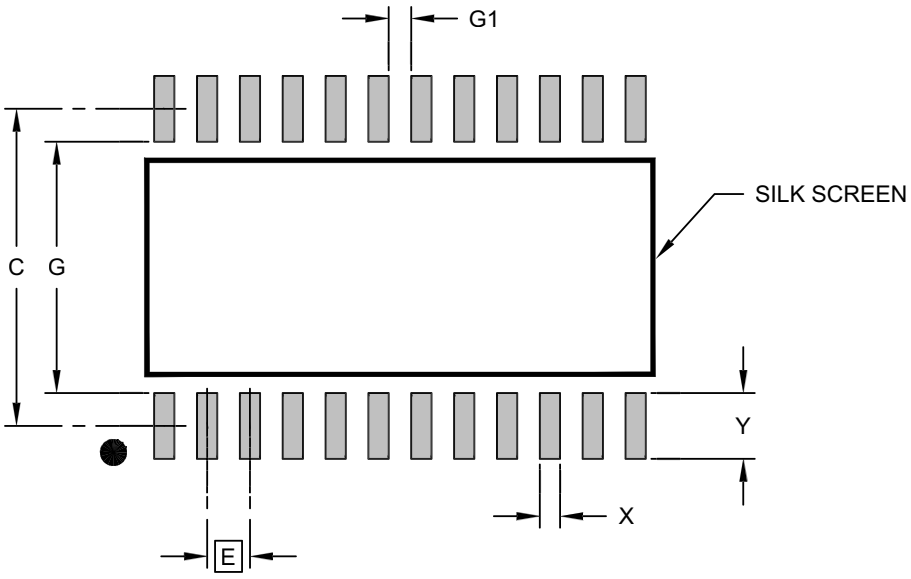
   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.

   REF: Reference Dimension, usually without tolerance, is for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-00025 [K3X] Rev F Sheet 2 of 2

24-Lead Plastic Small Outline (K3X) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width	X			0.60
Contact Pad Length	Y			2.00
Distance Between Pads	G1	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. The theoretically exact value is shown without tolerances.

Microchip Technology Drawing C04-02025 [K3X] Rev F

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (December 2025)

- Converted Micrel document LM2575 to Microchip data sheet DS20007078A.
- Minor text changes throughout.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

Part Number	[-X.X]	X	XX	[-XX]
Device	Output Voltage	Temp. Range	Package	Media Type

Device:	LM2575:		52 kHz Simple 1A Buck Regulator
Output Voltage:	3.3	=	3.3V
	5.0	=	5.0V
	12	=	12V
	<blank>	=	Adjustable
Temperature Range:	W	=	–40°C to +85°C (TO-220 and TO-263 only)
	Y	=	–40°C to +85°C (PDIP and SOIC only)
Package:	T	=	5-Lead TO-220
	U	=	5-Lead TO-263
	N	=	16-Lead PDIP
	WM	=	24-Lead Wide SOIC
Media Type:	<blank>	=	25/Tube (PDIP only)
	<blank>	=	31/Tube (SOIC only)
	<blank>	=	50/Tube (TO-220/263 only)
	TR	=	750/Reel (TO-263 only)
	TR	=	1,000/Reel (SOIC only)

Examples:

a) LM2575-3.3WU:

LM2575, 3.3V Output Voltage, –40°C to +85°C Temp. Range, 5-Lead TO-263, 50/Tube

b) LM2575YN:

LM2575, Adjustable Output Voltage, –40°C to +85°C Temp. Range, 16-Lead PDIP, 25/Tube

c) LM2575-12YWM-TR:

LM2575, 12V Output Voltage, –40°C to +85°C Temp. Range, 24-Lead Wide SOIC, 1,000/Reel

d) LM2575-5.0WT:

LM2575, 5.0V Output Voltage, –40°C to +85°C Temp. Range, 5-Lead TO-220, 50/Tube

e) LM2575YWM:

LM2575, Adjustable Output Voltage, –40°C to +85°C Temp. Range, 24-Lead Wide SOIC, 31/Tube

f) LM2575-3.3YN:

LM2575, 3.3V Output Voltage, –40°C to +85°C Temp. Range, 16-Lead PDIP, 25/Tube

g) LM2575WU-TR:

LM2575, Adjustable Output Voltage, –40°C to +85°C Temp. Range, 5-Lead TO-263, 750/Reel

Note: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

NOTES:

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